

April 2000

FQP33N10

100V N-Channel MOSFET

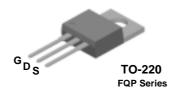
General Description

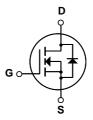
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor

Features

- 33A, 100V, $R_{DS(on)}$ = 0.052 Ω @V_{GS} = 10 V Low gate charge (typical 38 nC)
- Low Crss (typical 62 pF)
- · Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP33N10	Units	
V _{DSS}	Drain-Source Voltage		100	V	
I _D	Drain Current - Continuous (T _C = 25°	C)	33	А	
	- Continuous (T _C = 100°C)		23	А	
I _{DM}	Drain Current - Pulsed	(Note 1)	132	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	435	mJ	
I _{AR}	Avalanche Current	(Note 1)	33	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	12.7	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		127	W	
	- Derate above 25°C		0.85	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.18	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.11		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 100 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 80 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} =10 V, I _D =16.5 A		0.040	0.052	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 16.5 A (Note 4)		22		S
C _{iss} C _{oss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1150 320	1500 420	pF pF
C _{rss}	Reverse Transfer Capacitance			62	80	pF
	ing Characteristics			•		
t _{d(on)}	Turn-On Delay Time			15	40	ns
t _r	Turn-On Rise Time	$V_{DD} = 50 \text{ V}, I_D = 33 \text{ A},$		195	400	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$		80	170	ns
	Turn-Off Fall Time	(Note 4, 5)		110	230	ns
t _f						. 0
•	Total Gate Charge	$V_{DC} = 80 \text{ V. } I_{D} = 33 \text{ A}.$		38	51	nC
Q _g	Total Gate Charge Gate-Source Charge	$V_{DS} = 80 \text{ V}, I_{D} = 33 \text{ A},$ $V_{GS} = 10 \text{ V}$		38 7.5	51 	nC nC
Q _g	· ·	$V_{DS} = 80 \text{ V}, I_{D} = 33 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)			_	
Q _g Q _{gs} Q _{gd}	Gate-Source Charge Gate-Drain Charge	V _{GS} = 10 V (Note 4, 5)		7.5		nC
Q _g Q _{gs} Q _{gd} Drain-S	Gate-Source Charge Gate-Drain Charge Source Diode Characteristics and	V _{GS} = 10 V (Note 4, 5)		7.5		nC nC
Q _g Q _{gs} Q _{gd} Drain-S	Gate-Source Charge Gate-Drain Charge Source Diode Characteristics at Maximum Continuous Drain-Source Dio	V _{GS} = 10 V (Note 4, 5) nd Maximum Ratings ode Forward Current		7.5	33	nC nC
Q _g Q _{gs} Q _{gd} Drain-S	Gate-Source Charge Gate-Drain Charge Source Diode Characteristics as Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	V _{GS} = 10 V (Note 4, 5) nd Maximum Ratings ode Forward Current Forward Current		7.5	33	nC nC
$egin{array}{l} t_{ m f} & & & \\ Q_{ m g} & & & \\ Q_{ m gs} & & & \\ Q_{ m gd} & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ & & & & \\ $	Gate-Source Charge Gate-Drain Charge Source Diode Characteristics at Maximum Continuous Drain-Source Dio	V _{GS} = 10 V (Note 4, 5) nd Maximum Ratings ode Forward Current		7.5	33	nC nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 0.6mH, I $_{AS}$ = 33A, V $_{DD}$ = 25V, R $_{G}$ = 25 Ω . Starting T $_{J}$ = 25°C 3. I $_{SD}$ \leq 33A, di/dt \leq 300A/µs, V $_{DD}$ \leq BV $_{DSS}$, Starting T $_{J}$ = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

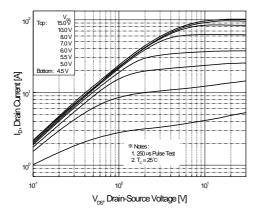


Figure 1. On-Region Characteristics

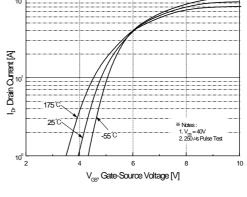


Figure 2. Transfer Characteristics

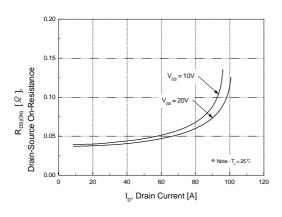


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

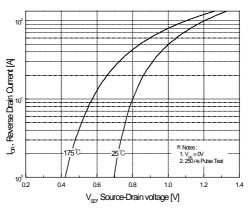


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

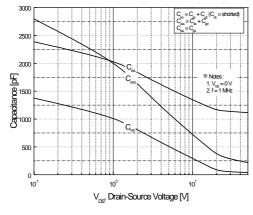


Figure 5. Capacitance Characteristics

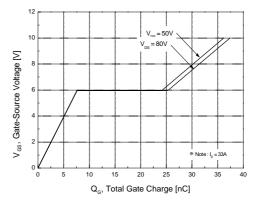
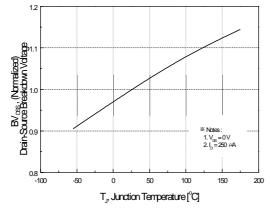


Figure 6. Gate Charge Characteristics

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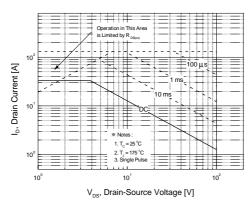
Typical Characteristics (Continued)



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Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



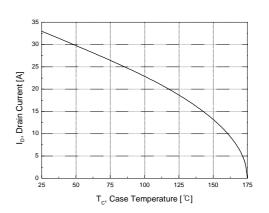


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

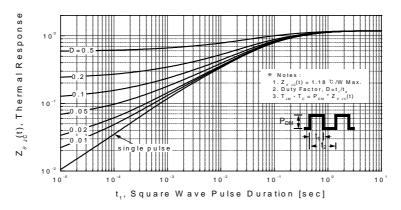
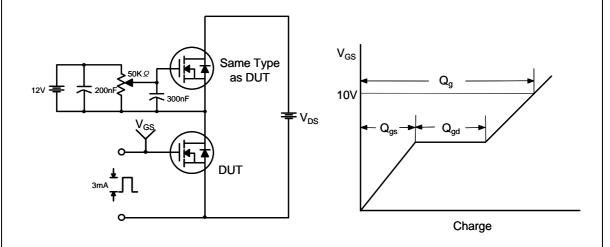


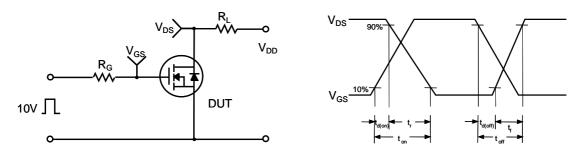
Figure 11. Transient Thermal Response Curve

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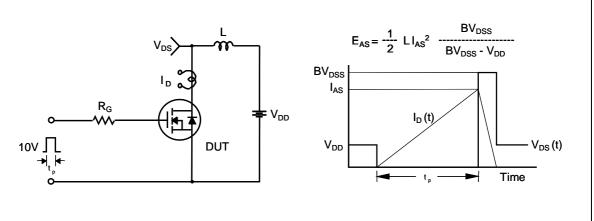
Gate Charge Test Circuit & Waveform



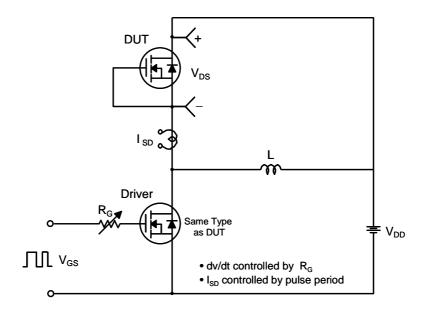
Resistive Switching Test Circuit & Waveforms

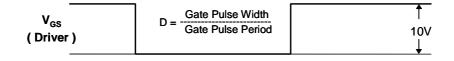


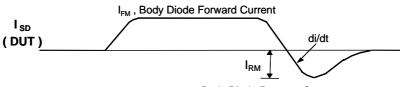
Unclamped Inductive Switching Test Circuit & Waveforms



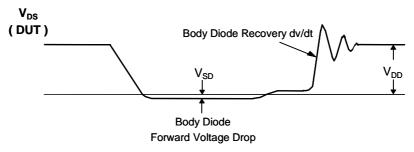
Peak Diode Recovery dv/dt Test Circuit & Waveforms







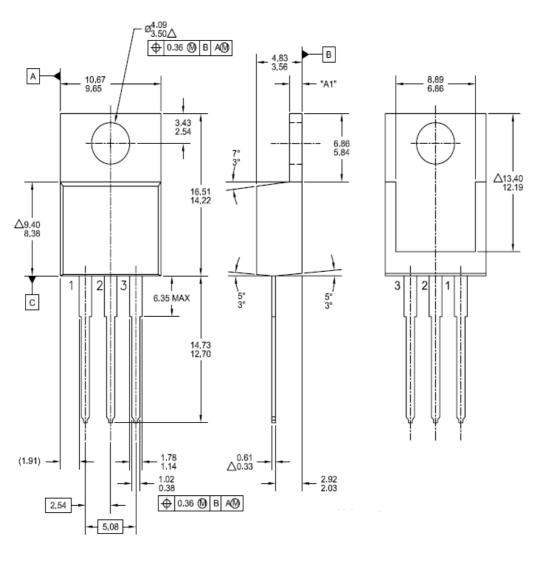
Body Diode Reverse Current

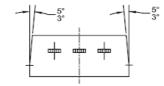


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Mechanical Dimensions

TO - 220





Dimensions in Millimeters

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